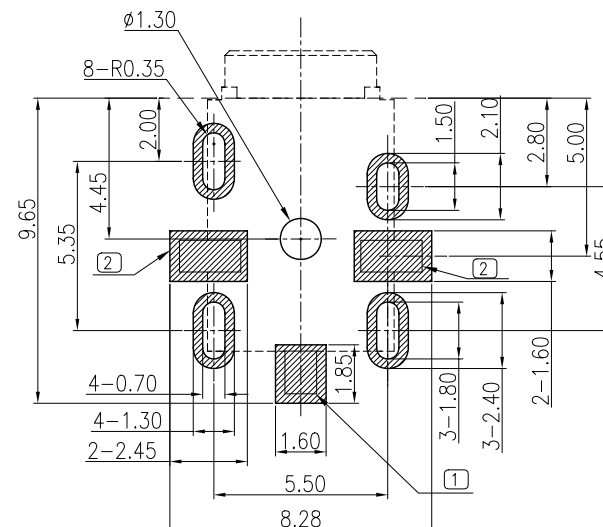
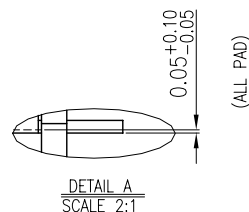
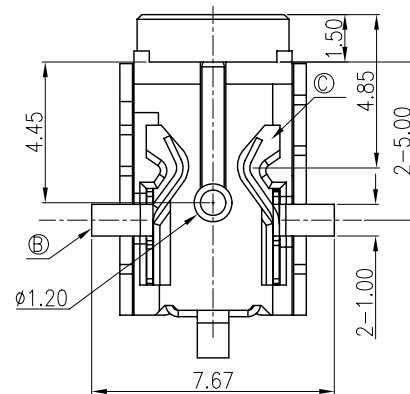
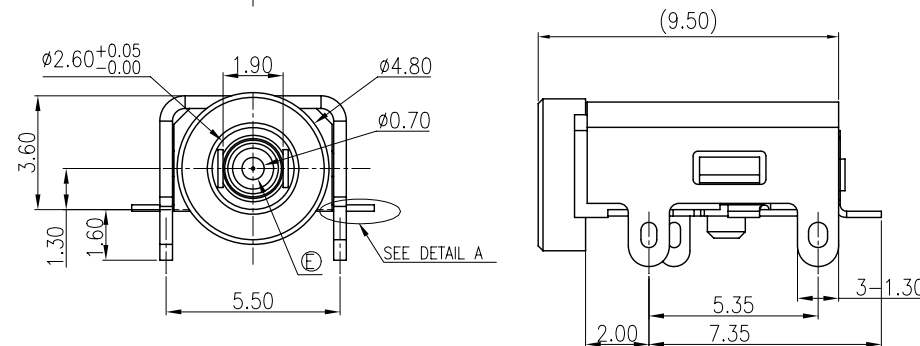
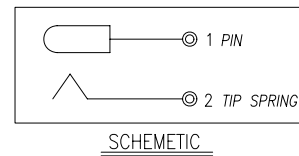


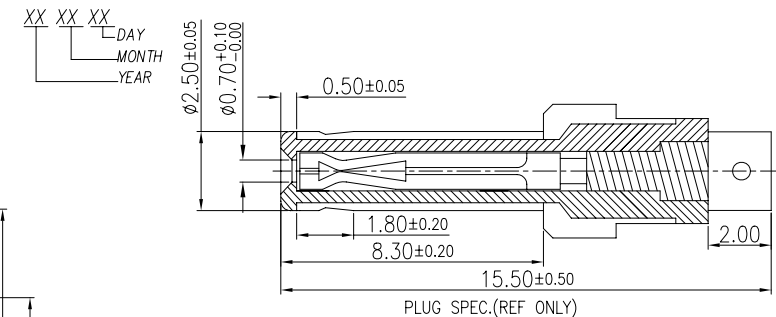
REV.	ECN NO OR DESCRIPTION	REVISED	DATE
A	INITIAL RELEASE	HAIHUA	5/14'09

NOTES:

1. MATERIAL:
 - 1.1 HOUSING:HIGH TEMP. THERMAL PLASTIC,UL94V-0,COLOR BLACK.
 - 1.2 TIP SPRING-A&TIP SPRING-B: COPPER ALLOY,T=0.20mm.
 - 1.3 TERMINAL: COPPER ALLOY,T=0.20.
 - 1.4 PIN: COPPER ALLOY.
 - 1.5 SHIELD: COPPER ALLOY.
2. FINISH:
 - 2.1 TIP SPRING-A&TIP SPRING-B: 60u" MIN. Ag PLATING ALLOVER.
60u"~180" NICKEL UNDERPLATING OVERALL;
 - 2.2 TERMINAL; 60u" MIN. Ag PLATING ALLOVER.
60u"~180" NICKEL UNDERPLATING OVERALL;
 - 2.3 PIN: 60u" MIN. Ag PLATING ALLOVER.
60u"~180" NICKEL UNDERPLATING OVERALL;
 - 2.4 SHIELD: Ni60u"~120u"
3. SPECIFICATION: SEE 2DC-2262 SERIES SPECIFICATION.
4. SOLDER HEAT RESISTANCE: REFLOW SOLDERING 260° FOR 10SEC.
- 5.TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.
6. HALOGEN FREE PRODUCT IDENTIFICATION MARK ON PRODUCT:
7. HALOGEN FREE PRODUCT IDENTIFICATION LABEL ON PACKAGING:
8. FOR REFLOW SOLDERING LEED FREE PROCESS.
9. ALL DIMENSIONS MUST BE INSPECTED BY QA,EXCEPT REF DIMENSIONS.
10. DATE CODE DESCRIPTION:



RECOMMENDED P.C.B. LAYOUT(PCB THICKNESS:1.2mm)
TOP VIEW (TOLRANCE: ±0.05)



F	SHELL	1	COPPER ALLOY,0.4T	Ni60u"~120u"
E	PIN	1	COPPER ALLOY,#0.70	60u" Ag MIN,60u"~180u"Ni
D	TERMINAL	1	COPPER ALLOY,0.20T	60u" Ag MIN,60u"~180u"Ni
C	TIP SPRING-B	1	COPPER ALLOY,0.20T	60u" Ag MIN,60u"~180u"Ni
B	TIP SPRING-A	1	COPPER ALLOY,0.20T	60u" Ag MIN,60u"~180u"Ni
A	HOUSING	1	HIGH TEMP. THERMAL PLASTIC	COLOR BLACK
NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR

UNLESS OTHERWISE
SPECIFIED TOLERANCES

Singatron Enterprise Co., Ltd.
信音企業股份有限公司

DECIMALS:		ANGLES:	
X	: ± 0.5	X	: $\pm 2^\circ$
X.X	: ± 0.3	X.X	: $\pm 1^\circ$
X.XX	: ± 0.2		

TITLE
DWN
CHKD
APVD

DC POWER JACK			
AIHUA 2009.5.14	PART NO. 2DC2263-000111		
	SCALE 6:1	UNIT: mm	
BOBIN 5/14/09	SIZE: A3	SHEET: 10F1	REV: A
CUSTOMER COPY			